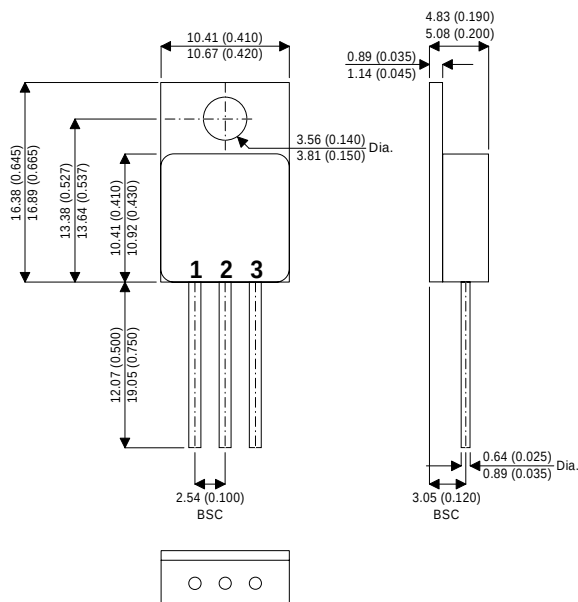


IRFY230

MECHANICAL DATA

Dimensions in mm (inches)



TO-257AA – Metal Package

Pad 1 – Gate Pad 2 – Drain Pad 3 – Source

N-CHANNEL POWER MOSFET FOR HI-REL APPLICATIONS

V_{DSS}	200V
$I_{D(cont)}$	9A
$R_{DS(on)}$	0.40Ω

FEATURES

- HERMETICALLY SEALED TO-257AA METAL PACKAGE
- SIMPLE DRIVE REQUIREMENTS
- LIGHTWEIGHT
- SCREENING OPTIONS AVAILABLE
- ALL LEADS ISOLATED FROM CASE

ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}C$ unless otherwise stated)

V_{GS}	Gate – Source Voltage	±20V
I_D	Continuous Drain Current @ $T_{case} = 25^{\circ}C$	9A
I_D	Continuous Drain Current @ $T_{case} = 100^{\circ}C$	6A
I_{DM}	Pulsed Drain Current	36A
P_D	Power Dissipation @ $T_{case} = 25^{\circ}C$	75W
	Linear Derating Factor	0.6W/°C
T_J, T_{stg}	Operating and Storage Temperature Range	–55 to 150°C
$R_{\theta JC}$	Thermal Resistance Junction to Case	1.67°C/W max..

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ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise stated)

Parameter		Test Conditions		Min.	Typ.	Max.	Unit
STATIC ELECTRICAL RATINGS							
BV _{DSS}	Drain – Source Breakdown Voltage	V _{GS} = 0	I _D = 1mA	200			V
ΔBV _{DSS}	Temperature Coefficient of Breakdown Voltage	Reference to 25°C I _D = 1mA			0.29		V/°C
R _{DS(on)}	Static Drain – Source On–State Resistance	V _{GS} = 10V	I _D = 6A			0.40	Ω
		V _{GS} = 10V	I _D = 9A			0.49	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS}	I _D = 250μA	2		4	V
g _{fs}	Forward Transconductance	V _{DS} ≥ 15V	I _{DS} = 6A	3			S(Ω)
I _{DSS}	Zero Gate Voltage Drain Current	V _{GS} = 0	V _{DS} = 0.8BV _{DSS}			25	μA
			T _J = 125°C			250	
I _{GSS}	Forward Gate – Source Leakage	V _{GS} = 20V				100	nA
I _{GSS}	Reverse Gate – Source Leakage	V _{GS} = –20V				-100	
DYNAMIC CHARACTERISTICS							
C _{iss}	Input Capacitance	V _{GS} = 0			600		pF
C _{oss}	Output Capacitance	V _{DS} = 25V			250		
C _{rss}	Reverse Transfer Capacitance	f = 1MHz			80		
Q _g	Total Gate Charge	V _{GS} = 10V I _D = 9A V _{DS} = 0.5BV _{DSS}		16		39	nC
Q _{gs}	Gate – Source Charge	I _D = 9A		3		5.1	nC
Q _{gd}	Gate – Drain (“Miller”) Charge	V _{DS} = 0.5BV _{DSS}		8		20	
t _{d(on)}	Turn–On Delay Time	V _{DD} = 100V I _D = 9A R _G = 7.5Ω				35	ns
t _r	Rise Time					80	
t _{d(off)}	Turn–Off Delay Time					60	
t _f	Fall Time					40	
SOURCE – DRAIN DIODE CHARACTERISTICS							
I _S	Continuous Source Current					9	A
I _{SM}	Pulse Source Current					36	
V _{SD}	Diode Forward Voltage	I _S = 9A T _J = 25°C V _{GS} = 0				1.4	V
t _{rr}	Reverse Recovery Time	I _S = 9A T _J = 25°C				500	ns
Q _{rr}	Reverse Recovery Charge	d _i / d _t ≤ 100A/μs V _{DD} ≤ 50V				6	μC
PACKAGE CHARACTERISTICS							
L _D	Internal Drain Inductance	(from 6mm down drain lead pad to centre of die)			8.7		nH
L _S	Internal Source Inductance	(from 6mm down source lead to centre of source bond pad)			8.7		

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